

03-29-1999

In place of Form PTO-1595

PATENT
DOCKET NUMBER: 22397.108

RECC

100995908

T - PATENTS

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document(s) or copy thereof:

1. Name of conveying party(ies):

Atsuyuki Fukano

2. Name and address of receiving party:

Ball Semiconductor, Inc.
415 Century Parkway
Allen, TX 75013

Additional name(s) & address(es) attached?
 Yes XXX No

3. Nature of conveyance: XXX Assignment

Execution Date: March 5, 1999

4. Application or patent number(s):

A. Patent Application No.(s):

B. Patent No.(s): 09/268770

5. Name and address of party to whom correspondence concerning document should be mailed:

David L. McCombs
Haynes and Boone, L.L.P.
3100 NationsBank Plaza
901 Main Street
Dallas, TX 75202-3789

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 40.00

X Enclosed
 Authorized to be charged to deposit account

8. Deposit account number: 08-1394
(Duplicate copy of this sheet is attached)

DO NOT USE THIS SPACE

9. Statement and signature:

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David M. O'Dell

David M. O'Dell, Reg. No. 42,044

3-15-99

Date

Total number of pages including cover sheet, attachments and document: 3

Mail document(s) to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Box Assignments
Washington, D. C. 20231

d-626050.1

03/24/1999 MAILIVER 00000006 09/268770 NO. OF OP 02 FC:501

jc530 U.S. PTO
09/268770
03/15/99

PATENT
REEL: 9839 FRAME: 0175

MRD 3/15/99

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made and filed herewith; and

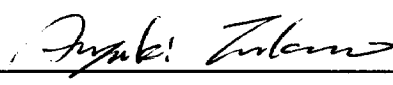
WHEREAS, Ball Semiconductor, Inc. a Texas Corporation having a place of business at 415 Century Parkway, Allen, Texas 75013 (hereinafter called Ball Semiconductor), is desirous of acquiring my entire right, title and interest in and to the invention, and to the application and any Letters Patent that may issue thereon;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to Ball Semiconductor, its successors and assigns, my entire right, title and interest in and to the invention and in to the application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to Ball Semiconductor, as assignee of my entire right, title and interest.

I also hereby sell and assign to Ball Semiconductor, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to Ball Semiconductor, or to its successors, assigns, and legal representatives, any facts know to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawfully papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid Ball Semiconductor, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	MAGNETIC ALIGNMENT SYSTEM FOR BUMPS ON AN INTEGRATED CIRCUIT DEVICE
INVENTOR SIGNATURE AND NAME	Atsuyuki Fukano 
DATE	5 March '99
RESIDENCE (City, State)	7-26-2 Hirai Edogawa-ku Tokyo, Japan

d-623065.1